

## Solder Wire Pb93.5/Sn5/Ag1.5 No-Clean with 2.0% Flux Core 1lb Spool

### Product Highlights

#### No-Clean Synthetic Flux Core

The clear, non-corrosive, non-conductive residue is meant to be left on the board.

2.0% flux core

Halogen content: None

### Specifications

Alloy:	Pb93.5/Sn5/Ag1.5
Wire Diameter:	0.031" (0.8mm)
Flux Type:	No-Clean Synthetic
Flux Classification:	ROL0
Melting Point:	296-301°C (565-574°F)
Packaging:	1 lb spool

### Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains Lead (Pb) CAS# 7439-92-1 No other SVHC present

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 2 Directive 2011/65/EU:	No